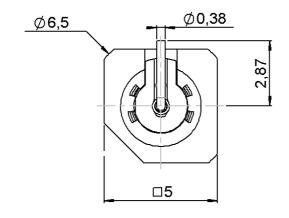
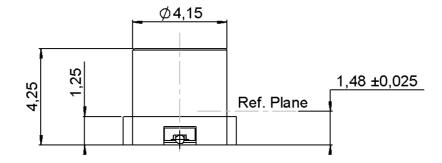
R222.941.324

LIMITED DETENT -TAPE AND REEL BY 500

Series: SMP-COM



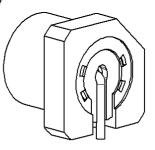


Production according to procedure PAQP-C-017



Scale 1:1

Coaxial connector will not go over 0.5ppm at 10mm under a magnetic field of 1.5T



All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (μm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS	NON MAGNETIC BRONZE BERYLLIUM COPPER - PEEK	GOLD 1.3 OVER COPPER 2.5 GOLD 1.3 OVER COPPER 2.5

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In the effort to improve our products, we reserve the right to make changes judged to be

necessary.



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PACKAGING

Unit Other

Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

50 Ω

Frequency 0-12.4* GHz

VSWR 1.1 ** + **0,0000** x F(GHz) Maxi

Insertion loss **0.12** $\sqrt{F(GHz)}$ dB Maxi

NA - F(GHz)) dB Maxi RF leakage 335 Veff Maxi

Voltage rating Dielectric withstanding voltage 500 Veff mini Insulation resistance **5000** MΩ mini

ENVIRONMENTAL

-55/+125 ° C Operating temperature

Hermetic seal NA Atm.cm3/s

Panel leakage NA

OTHER CHARACTERISTICS

Assembly instruction

Others:

*ROS 1.35 at 12.4GHz

**ROS at 6GHz

Maximum DC current: 7 Amps

MECHANICAL CHARACTERISTICS

Center contact retention

Standard

500

Impedance

Axial force – Mating end **6.8** N mini Axial force – Opposite end **6.8** N mini Torque NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 100 Cycles mini

Weight **0,3310** g

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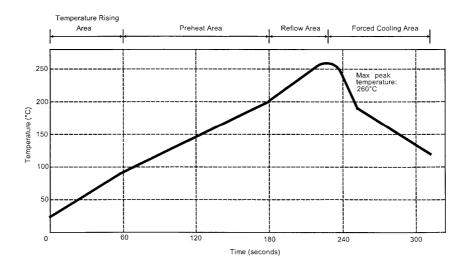
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SOLDER PROCEDURE

- 1. Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
 - We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. This process of soldering has been tested with convection oven .Below please find ,the typical profile to use.
- 4. The cleaning of printed circuit boards is not obliged .
- 5. Verification of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

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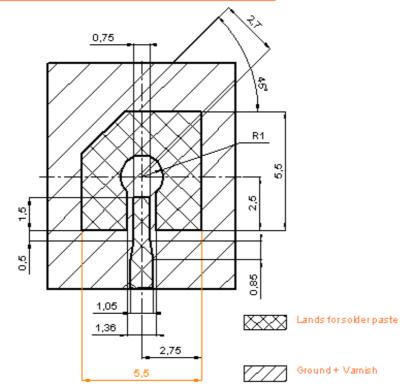


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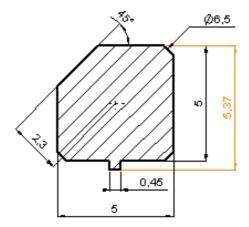
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STANDARD PAD(For ROGERS 4350)



SHADOW OF RECEPTACLE FOR VIDEO CAMERA



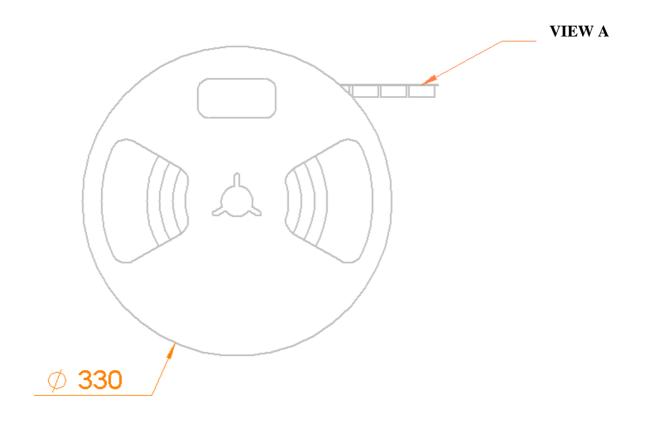
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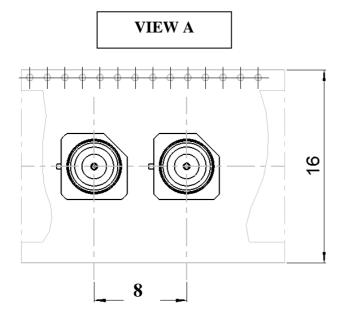


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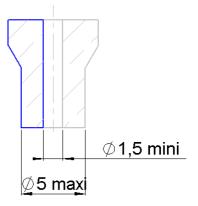
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